

|                               |
|-------------------------------|
| <b>APPLICATION DATA SHEET</b> |
|-------------------------------|

Electronic Version v14

Stylesheet Version v14.0

|                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |                                                                                                       |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------|
| <b>Title of<br/>Invention</b>                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                  | Method of manufacturing semiconductor device and cutting<br>apparatus for cutting semiconductor wafer |
| Application Type:            regular, utility<br>Attorney Docket Number: 36395                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                 |                                                                                                       |
| Correspondence address:<br><br>Customer Number:                            116                            *116*                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |                                                                                                       |
| Priority Data:<br><br>Doc.No: 2003-014567; Country - JP; Date: 2003-01-23 us-priority-claimed                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                  |                                                                                                       |
| Inventor Information:<br><br><u>Inventor 1:</u><br>Applicant Authority Type:            Inventor<br>Citizenship:                            JP<br>Given Name:                            Kiyoshi<br>Family Name:                            Arita<br>City of Residence:                    Fukuoka<br>Country of Residence:                JP<br>Address-1 of Mailing Address: 5-10-2, Higashifukuma, Fukuma-machi<br>Address-2 of Mailing Address: Munakata-gun<br>City of Mailing Address:            Fukuoka<br>State of Mailing Address:<br>Postal Code of Mailing Address: 811-3225<br>Country of Mailing Address:        JP<br>Phone:<br>Fax:<br>E-mail: |                                                                                                       |

**Attorney Information:**

| <b>Name</b>      | <b>Registration Number</b> |
|------------------|----------------------------|
| Jeffrey J. Sopko | 27676                      |

**Assignee 1:**

**Organization Name:** Matsushita Electric Industrial Co., Ltd.  
**Address-1 of Mailing Address:** 1006, Oaza Kadoma  
**Address-2 of Mailing Address:** Kadoma-shi  
**City of Mailing Address:** Osaka  
**State of Mailing Address:**  
**Postal Code of Mailing Address:** 571-8501  
**Country of Mailing Address:** JP  
**Phone:**  
**Fax:**  
**E-mail:**